

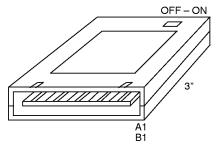
DS1217ANonvolatile Read/Write Cartridge

FEATURES

- User-insertable
- Capacity up to 32K x 8
- Standard bytewide pinout facilitates connection to JEDEC 28-pin DIP socket via ribbon cable
- Data retention greater than 10 years
- Automatic write protection circuitry safeguards against data loss
- Manual switch unconditionally protects data
- · Compact size and shape
- Rugged and durable
- Wide operating temperature range of 0°C to 70°C

PIN ASSIGNMENT

Name	Po	siti	on	Name
Ground	A1		B1	No Connect
+5 Volts	A2		B2	Address 14
Write Enable	А3		ВЗ	Address 12
Address 13	A4		B4	Address 7
Address 8	A5		B5	Address 6
Address 9	A6		B6	Address 5
Address 11	A7		В7	Address 4
Output Enable	A8		B8	Address 3
Address 10	A9		В9	Address 2
Cartridge Enable	A10		B10	Address 1
Data I/O 7	A11		B11	Address 0
Data I/O 6	A12		B12	Data I/O 0
Data I/O 5	A13		B13	Data I/O 1
Data I/O 4	A14		B14	Data I/O 2
Data I/O 3	A15		B15	Ground



See Mech. Drawings Section

DESCRIPTION

The DS1217A is a nonvolatile RAM designed for portable applications requiring a rugged and durable package. The nonvolatile cartridge is available in densities ranging from 2K x 8 to 32K x 8 in 8K byte increments. A card edge connector is required for connection to a host system. A standard 30-pin connector can be used for direct mount to a printed circuit board. Alternatively, remote mounting can be accomplished with a 28-conductor ribbon cable terminated with a 28-pin DIP plug. The

remote method can be used to retrofit existing systems that have JEDEC 28-pin bytewide memory sites.

The DS1217A cartridge has a lifetime energy source to retain data and circuitry needed to automatically protect memory contents. Reading and writing the memory locations is the same as using conventional static RAM. If the user wants to convert from read/write memory to read-only memory, a manual switch is provided to unconditionally protect memory contents.

030598 1/8

READ MODE

The DS1217A executes a read cycle whenever \overline{WE} (write enable) is inactive (high) and \overline{CE} (cartridge enable) is active (low). The unique address specified by the 15 address inputs (A0-A14) defines which of the 32,768 bytes of data is to be accessed. Valid data will be available to the eight data I/O pins within t_{ACC} (access time) after the last address input signal is stable, providing that \overline{CE} and \overline{OE} (output enable) access times are also satisfied. If \overline{OE} and \overline{CE} times are not satisfied, then data access must be measured from the latter occurring signal (\overline{CE} or \overline{OE}); the limiting parameter is either t_{CO} for \overline{CE} or t_{OE} for \overline{OE} rather than address access. Read cycles can only occur when V_{CC} is greater than 4.5 volts. When V_{CC} is less than 4.5 volts, the memory is inhibited and all accesses are ignored.

WRITE MODE

The DS1217A is in the write mode whenever both the WE and CE signals are in the active (low) state after address inputs are stable. The last falling edge to occur of either $\overline{\text{CE}}$ or $\overline{\text{WE}}$ will determine the start of the write cycle. The write cycle is terminated by the first rising edge of either CE or WE. All address inputs must be kept valid throughout the write cycle. WE must return to the high state for a minimum recovery time (twR) before another cycle can be initiated. The OE control signal should be kept inactive (high) during write cycles to avoid bus contention. However, if the output bus has been enabled (CE and OE active) then WE will disable the outputs in t_{ODW} from its falling edge. Write cycles can only occur when V_{CC} is greater than 4.5 volts. When V_{CC} is less than 4.5 volts, the memory is write protected.

DATA RETENTION MODE

The Nonvolatile Cartridge provides full functional capability for V_{CC} greater than 4.5 volts and guarantees write protection for V_{CC} less than 4.5 volts. Data is maintained in the absence of V_{CC} without any additional support circuitry. The DS1217A constantly monitors V_{CC} . Should the supply voltage decay, the RAM is automatically write protected below 4.5 volts. As V_{CC} falls below approximately 3.0 volts, the power switching circuit connects a lithium energy source to RAM. To retain data

during power-up, when V_{CC} rises above approximately 3.0 volts, the power switching circuit connects the external V_{CC} to the RAM and disconnects the lithium energy source. Normal RAM operation can resume after V_{CC} exceeds 4.5 volts.

The DS1217A checks battery status to warn of potential data loss. Each time that $V_{\rm CC}$ power is restored to the cartridge, the battery voltage is checked with a precision comparator. If the battery supply is less than 2.0 volts, the second memory cycle is inhibited. Battery status can, therefore, be determined by performing a read cycle after power-up to any location in memory, recording that memory location content. A subsequent write cycle can then be executed to the same memory location, altering data. If the next read cycle fails to verify the written data, the contents of the memory are questionable.

In many applications, data integrity is paramount. For this reason, the cartridge provides battery redundancy. The DS1217A features an internal isolation switch that provides for the connection of two batteries. During battery backup time, the battery with the highest voltage is selected for use. If one battery fails, the other will automatically take over. The switch between batteries is transparent to the user. A battery status warning will occur if both batteries are less than 2.0 volts.

REMOTE CONNECTION VIA A RIBBON CABLE

Existing systems that contain 28-pin bytewide sockets can be retrofitted using a 28-pin DIP plug. The DIP plug, AMP Part Number 746616-2, can be inserted into the 28-pin site after the memory is removed. Connection to the cartridge is accomplished via a 28-pin ribbon cable connected to a 30-contact card edge connector, AMP Part Number 499188-4. The 28-pin ribbon cable must be right-justified such that positions A1 and B1 are left disconnected. For applications where the cartridge is installed or removed with power applied, both ground contacts (A1 and B15) on the card edge connector should be grounded to further enhance data integrity. Access time push-out may occur as the distance between the cartridge and driving circuitry is increased.

030598 2/8

CARTRIDGE NUMBERING Table 1

PART NO.	DENSITY	UNUSED ADDRESS INPUTS
DS1217A/16K-25	2K x 8	*Address 11, 12, 13, 14
DS1217A/64K-25	8K x 8	*Address 13, 14
DS1217A/128K-25	16K x 8	*Address 14
DS1217A/192K-25	24K x 8	
DS1217A/256K-25	32K x 8	

^{*}Unused address inputs must be held low (V_{IL}).

030598 3/8

ABSOLUTE MAXIMUM RATINGS*

Voltage on Any Connection Relative to Ground
Operating Temperature
Storage Temperature

O°C to 70°C
-40°C to +70°C

RECOMMENDED DC OPERATING CONDITIONS

(0°C to 70°C)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Power Supply Voltage	V _{CC}	4.5	5.0	5.5	٧	
Input High Voltage	V _{IH}	2.2		V _{CC}	V	
Input Low Voltage	V _{IL}	0.0		+0.8	٧	

DC ELECTRICAL CHARACTERISTICS

(0°C to 70°C; $V_{CC} \text{=-}5V \pm 10\%)$

PARAMETER	SYMBOL	MIN	TYP	MAX.	UNITS	NOTES
Input Leakage Current	կլ	-60		+60	μΑ	
$\begin{array}{ c c }\hline I/O \text{ Leakage Current}\\\hline \overline{CE} \geq V_{IH} \leq V_{CC}\\\hline \end{array}$	I _{IO}	-10		+10	μА	
Output Current @ 2.4V	I _{OH}	-1.0	-2.0		mA	
Output Current @ 0.4V	l _{OL}	2.0	3.0		mA	
Standby Current CE=2.2V	I _{CCS1}		5.0	10	mA	
Operating Current	I _{CCO1}		35	75	mA	

CAPACITANCE $(t_A = 25^{\circ}C)$

						\7
PARAMETER	SYMBOL	MIN	TYP	MAX.	UNITS	NOTES
Input Capacitance	C _{IN}			75	pF	
Input/Output Capacitance	C _{I/O}			75	pF	

030598 4/8

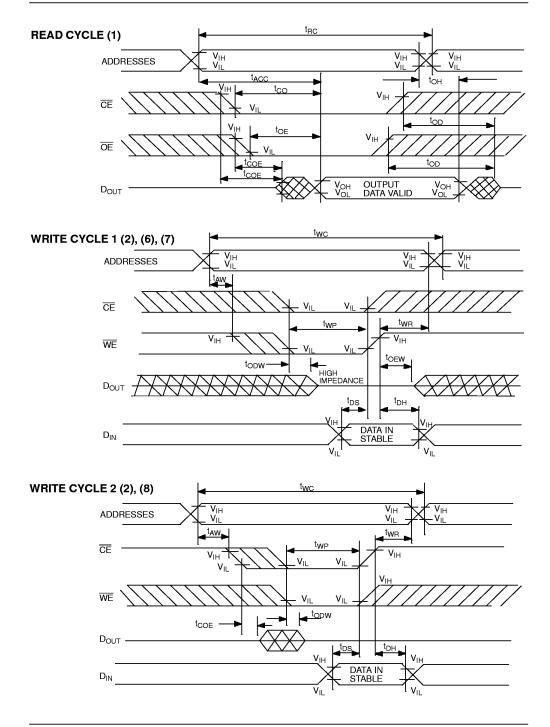
^{*} This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operation sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

AC ELECTRICAL CHARACTERISTICS

(0°C to 70°C; V $_{CC}$ =5V \pm 10%)

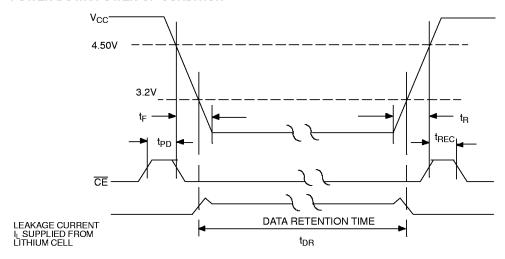
PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Read Cycle Time	t _{RC}	250			ns	
Access Time	t _{ACC}			250	ns	
OE to Output Valid	t _{OE}			125	ns	
CE to Output Valid	tco			250	ns	
OE or CE to Output Active	t _{COE}	5			ns	5
Output High Z from Deselection	t _{OD}			125	ns	5
Output Hold from Address Change	t _{OH}	5			ns	
Write Cycle Time	t _{WC}	250			ns	
Write Pulse Width	t _{WP}	170			ns	3
Address Setup Time	t _{AW}	0			ns	
Write Recovery Time	t _{WR}	20			ns	
Output High Z from WE	t _{ODW}			100	ns	5
Output Active from WE	toew	5			ns	5
Data Setup Time	t _{DS}	100			ns	4
Data Hold Time from WE	t _{DH}	20			ns	4

030598 5/8



030598 6/8

POWER-DOWN/POWER-UP CONDITION



POWER-DOWN/POWER-UP TIMING

(0°C to 70°C)

SYM	PARAMETER	MIN	MAX	UNITS	NOTES
t _{PD}	CE at V _{IH} before Power-Down	0		μs	10
t _F	V_{CC} Slew from 4.5V to 0V (\overline{CE} at V_{IH})	100		μs	
t _R	V_{CC} Slew from 0V to 4.5V (\overline{CE} at V_{IH})	0		μs	
t _{REC}	CE at V _{IH} after Power-Up	2	125	ms	10

 $(t_A = 25^{\circ}C)$

SYM	PARAMETER	MIN	MAX	UNITS	NOTES
t _{DR}	Expected Data Retention Time	10		years	9

WARNING:

Under no circumstances are negative undershoots, of any amplitude, allowed when the device is in battery backup mode.

NOTES:

- 1. WE is high for a read cycle.
- 2. $\overline{OE} = V_{IH}$ or V_{IL} . If $\overline{OE} = V_{IH}$ during the write cycle, the output buffers remain in a high impedance state.
- 3. t_{WP} is specified as the logical AND of $\overline{\text{CE}}$ and $\overline{\text{WE}}$. t_{WP} is measured from the latter of $\overline{\text{CE}}$ or $\overline{\text{WE}}$ going low to the earlier of $\overline{\text{CE}}$ or $\overline{\text{WE}}$ going high.
- 4. t_{DH}, t_{DS} are measured from the earlier of $\overline{\text{CE}}$ or $\overline{\text{WE}}$ going high.
- 5. These parameters are sampled with a 5pF load and are not 100% tested.
- 6. If the $\overline{\text{CE}}$ low transition occurs simultaneously with or later than the $\overline{\text{WE}}$ low transition in Write Cycle 1, the output buffers remain in a high impedance state during this period.
- 7. If the $\overline{\text{CE}}$ high transition occurs prior to or simultaneously with the $\overline{\text{WE}}$ high transition in Write Cycle 1, the output buffers remain in a high impedance state during this period.
- 8. If WE is low or the WE low transition occurs prior to or simultaneously with the CE low transition, the output buffers remains in a high impedance state during this period.
- Each DS1217A is marked with a 4-digit date code AABB. AA designates the year of manufacture; BB designates the week of manufacture. The expected t_{DR} is defined as starting at the date of manufacture.
- 10. Removing and installing the cartridge with power applied may disturb data.

DC TEST CONDITIONS

Outputs Open t Cycle = 250ns All Voltages Are Referenced to Ground

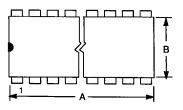
AC TEST CONDITIONS

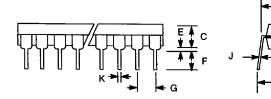
Output Load: 100pF + 1TTL Gate Input Pulse Levels: 0 - 3.0V Timing Measurement Reference Levels

Input: 1.5 V

030598 8/8

8- TO 28-PIN DIP (300 MIL)





Includes:		
DS1000	DS1211	DS1621
DS1000M	DS1215	DS1625
DS1003	DS1221	DS1632
DS1003M	DS1222	DS1640
DS1004M	DS1228	DS1651
DS1005	DS1229	DS1652
DS1005M	DS1231	DS1652B
DS1007	DS1232	DS1653
DS1010	DS1232LP	DS1666
DS1012M	DS1234	DS1667
DS1013	DS1236	DS1669
DS1013M	DS1237	DS1802
DS1020	DS1238	DS1830
DS1033M	DS1239	DS1832
DS1035M	DS1259	DS1867
DS1040M	DS1267	DS1868
DS1044	DS1275	DS1869
DS1045	DS1291	DS2009D
DS1200	DS1293	DS2010D
DS1206	DS1336	DS2011D
DS1210	DS1620	DS2013D

PKG	8-1	NIN	10-	PIN	14-	PIN	16-	PIN
DIM	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX
A IN.	0.360	0.400	0.480	0.520	0.740	0.780	0.740	0.780
MM	9.14	10.16	12.19	13.21	18.80	19.81	18.80	19.81
B IN.	0.240	0.260	0.240	0.260	0.240	0.260	0.240	0.260
MM	6.10	6.60	6.10	6.60	6.10	6.60	6.10	6.60
C IN.	0.120	0.140	0.120	0.140	0.120	0.140	0.120	0.140
MM	3.05	3.56	3.05	3.56	3.05	3.56	3.05	3.56
D IN.	0.300	0.325	0.300	0.325	0.300	0.325	0.300	0.325
MM	7.62	8.26	7.62	8.26	7.62	8.26	7.62	8.26
E IN.	0.015	0.040	0.015	0.040	0.015	0.040	0.015	0.040
MM	0.38	1.02	0.38	1.02	0.38	1.02	0.38	1.02
FIN.	0.120	0.140	0.110	0.130	0.120	0.140	0.120	0.140
MM	3.04	3.56	2.79	3.30	3.04	3.56	3.04	3.56
G IN.	0.090	0.110	0.090	0.110	0.090	0.110	0.090	0.110
MM	2.29	2.79	2.29	2.79	2.29	2.79	2.29	2.79
H IN	0.320	0.370	0.320	0.370	0.320	0.370	0.320	0.370
MM	8.13	9.40	8.13	9.40	8.13	9.40	8.13	9.40
J IN	0.008	0.012	0.008	0.012	0.008	0.012	0.008	0.012
MM	0.20	0.30	0.20	0.30	0.20	0.30	0.20	0.30
K IN.	0.015	0.021	0.015	0.021	0.015	0.021	0.015	0.021
MM	0.38	0.53	0.38	0.53	0.38	0.53	0.38	0.53

Continued on following page.

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MECHANICAL DRAWINGS

PKG	18-	PIN	20-	-PIN 24-Pii		PIN	28-	PIN
DIM	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX
A IN.	0.890	0.920	0.970	1.040	1.150	1.260	1.345	1.370
MM	22.61	23.36	24.63	26.42	29.21	32.00	34.16	34.80
B IN.	0.240	0.260	0.240	0.270	0.250	0.270	0.270	0.295
MM	6.10	6.60	6.09	6.86	6.35	6.86	6.85	7.49
C IN.	0.120	0.140	0.120	0.140	0.120	0.140	0.120	0.140
MM	3.05	3.56	3.05	3.56	3.05	3.56	3.05	3.56
D IN.	0.300	0.325	0.295	0.325	0.300	0.325	0.300	0.325
MM	7.62	8.26	7.49	8.26	7.62	8.26	7.62	8.26
E IN.	0.015	0.040	0.015	0.040	0.015	0.040	0.015	0.050
MM	0.38	1.02	0.38	1.02	0.38	1.02	0.38	1.27
F IN.	0.120	0.140	0.120	0.140	0.125	0.135	0.125	0.135
MM	3.04	3.56	3.04	3.56	3.18	3.48	3.18	3.48
G IN.	0.090	0.110	0.090	0.110	0.090	0.110	0.090	0.110
MM	2.23	2.79	2.23	2.79	2.23	2.79	2.23	2.79
H IN	0.320	0.370	0.310	0.390	0.320	0.370	0.320	0.370
MM	8.13	9.40	7.87	9.91	8.13	9.40	8.13	9.40
J IN	0.008	0.012	0.008	0.012	0.008	0.012	0.008	0.012
MM	0.20	0.30	0.20	0.30	0.20	0.30	0.20	0.30
K IN.	0.015	0.021	0.015	0.021	0.015	0.022	0.015	0.022
MM	0.38	0.53	0.38	0.53	0.38	0.56	0.38	0.56